



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC070N10NS5	<b>Issued</b>	13. April 2021
<b>MA#</b>	MA003954982		
<b>Package</b>	PG-TDSON-8-50	<b>Weight*</b>	106.57 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.848	0.80	0.80	7957	7957
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		512	
	non noble metal	iron	7439-89-6	1.090	1.02		10231	
	non noble metal	copper	7440-50-8	44.271	41.54	42.62	415420	426291
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	395	395
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		796	
	plastics	epoxy resin	-	3.903	3.66		36626	
	inorganic material	silicondioxide	60676-86-0	38.438	36.07	39.81	360683	398105
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11858	11858
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	272	272
solder	noble metal	silver	7440-22-4	0.030	0.03		284	
	non noble metal	tin	7440-31-5	0.061	0.06		568	
	non noble metal	lead	7439-92-1	1.120	1.05	1.14	10510	11362
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.34		3450	
	non noble metal	copper	7440-50-8	14.930	14.01	14.37	140094	143760
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com